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#### 1 Statement

HYCON Technology Corporation positions ourselves as a leading manufacturer of high precision integrated circuits in analog and digital signal processing applications.

Our quality system is in full accordance with ISO 9001: 2015 procedures. Our products are not only innovative and leading-edge from a design perspective, but they are also, based on our reliability data, exceptionally robust and conform to industrial standards resulted from their high stability. HYCON Technology Corporation strives to produce reliable and high-quality products that meet customers' requirements.

Due to the rising environmental and human rights concerns around the world, the need for environmental protection and hazardous (banned) substance elimination in electronic components and systems is receiving increased attention within the semiconductor and electronics industries. HYCON Technology Corporation asserts the concept of sustainable corporate development and social responsibility and respects international human rights therefore we not only have been devoted to the provision of Green products which are in compliance with Restriction of Hazardous Substances (RoHS) Directive (EU) 2016/293, (EU) 2015/863, 2011/65/EU, Halogen Free (IEC 61249-2-21) and REACH 1907/2006(EC) ANNEX XVII and SVHC (Substance of Very High Concern) under REACH (Registration, Evaluation, Authorization and Restriction of Chemicals) current version of restricted substances and prescribed regulations but also all products supplied to customers are of conflict-free minerals.

If necessary, please contact HYCON Technology Corporation's sales/agents for more information, and we will keep on providing our best support and service to you.

Arch Huang

Senior Director,

Quality Assurance Division.

HYCON TECHNOLOGY CORPORATION

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#### 2 ISO Certificate

Audited by creditworthy TÜV SUD Asia Pacific Ltd. TÜV Süddeutschland Group, HYCON Technology Corporation procured the anticipating certificate of ISO 9001: 2015.

HYCON Technology Corporation is certified in the scope of "Design, Manufacturing, Marketing and Service of Integrated Circuits".

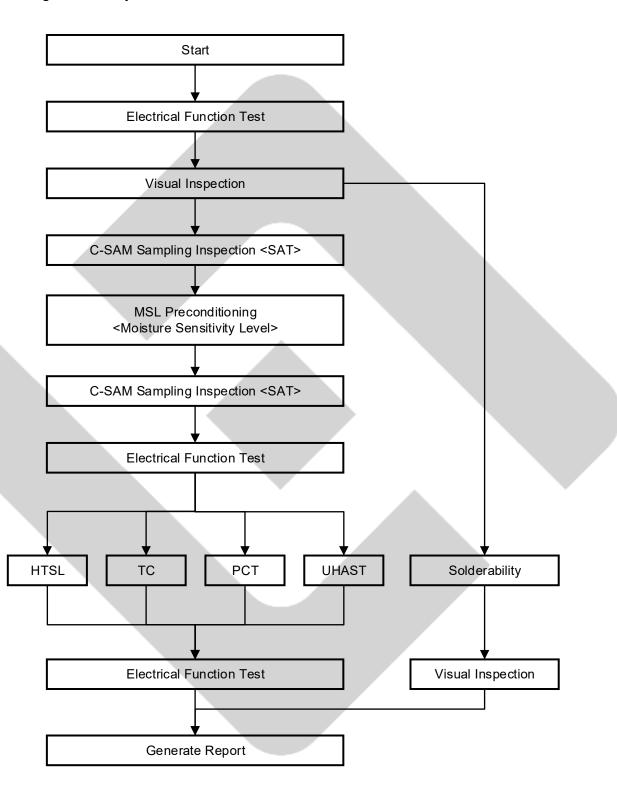
By fulfilling ISO 9001: 2015, it is the very first stage of quality management system of HYCON Technology Corporation. We're going to continuously practice quality objective, "Ceaseless Quality Improvement", "Fearless in Confronting Challenges", "Innovative Thinking" and "Sticking to Commitment" in every products realization and company evolving activities. HYCON Technology Corporation devotes to provide customers, representatives, suppliers with total satisfaction.





#### 3 Reliability Test Introduction

3.1 Package Reliability Test Flow



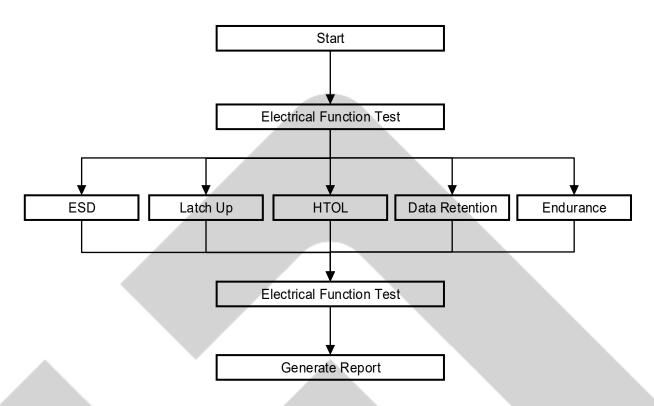


#### 3.2 Package Reliability Test Plan

Test Item	Reference Document	Test Condition and Readout	Sampling Plan		
rest item	Reference Document	rest Condition and Readout	SS/Acc.	LTPD	
MSL Preconditioning (PC)	JESD22-A113 IPC/JEDEC J-STD-020	Temperature Cycling:  -65°C∼150°C, 5 cycles  Bake: 125°C, 24 hrs.  Soaking: (MSL1 or MSL3)  MSL1: 85°C, 85%RH, 168 hrs.  MSL3: 30°C, 60%RH, 192 hrs.  Reflow: 3 times @ 260°C Peak	231/0	1%	
High Temperature Storage Life (HTSL)	JESD22-A103	150°C, 1000 hrs.	25/0	10%	
Temperature Cycling (TC)	MIL-STD-883 Method 1010 JESD22-A104	-65°C∼150°C, 500 cycles	25/0	10%	
Pressure Cooker Test (PCT)	JESD22-A102	121°C, 100%RH, 2atm, 168hrs.	25/0	10%	
High Temperature Accelerated Stress Test (UHAST)	JESD22-A118	130°C, 85%RH, 96 hrs.	25/0	10%	
Solderability (SD)	JESD22-B102	5 ± 0.5 sec.	15/0	15%	



#### 3.3 Product Reliability Test Flow



#### 3.4 Product Reliability Test Plan

Test Item	Reference Document	Test Spec and Stress Condition	SS/Acc.	
ESD-HBM	MIL-STD-883 Method 3015	It is presented until condition we	3/0	
ESD-MM	JESD22-A115	It is proceeded until condition we	3/0	
Latch-Up	JESD78	can carry out using test equipment.	3/0	
High Temperature	MIL-STD-883 Method 1005		77/0	
Operating Life	JESD22-A108	125°C, 1000 hrs.	77/0	
(HTOL)	JESD85		LTPD 3%	
Data Datantian	MIL-STD-883 Method 1008	450°C 4000 has	77/0	
Data Retention	JESD22-A117	150°C, 1000 hrs.	LTPD 3%	
Non-Volatile		40°C +35°C +95°C	77/0	
Memory Cycling	JESD22-A117	-40°C, +25°C, +85°C	77/0	
Endurance		100K Cycles	LTPD 3%	



#### 4 Product Information

#### 4.1 Package Reliability Result

Model	Tyme	Pins	Material	Package Reliability					
Wodei	Туре		Composition	MSL	HTSL	TC	PCT	UHAST	SD
HY14EXXX-W000	Wafer	-	Green	-	-	-	-	-	-
HY14EXXX-D000	Die	-	Green	-	-	-	-	-	-
HY14EXXX-E016	SSOP	16	Green	3	PASS	PASS	PASS	PASS	PASS
HY14EXXX-N016	QFN	16	Green	3	PASS	PASS	PASS	PASS	PASS

#### 4.2 Product Reliability Result

Test Item	Result
ESD-HBM	Pass ± 4KV
ESD-MM	Pass ± 400V
Latch-Up	Pass ± 200mA
High Temperature Operating Life	At 90% Confidence Level
(HTOL)	λ = 113.58 FIT
TOL)	MTTF = 1,005 years
Data Retention	>10 Years @ 85°C
Endurance	>100K Cycles @ -40°C ~ +85°C



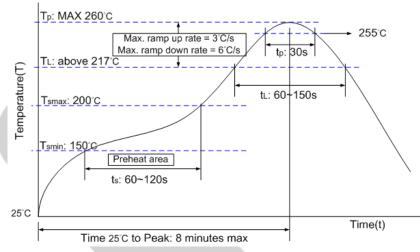
#### 4.3 Product Storage Condition

#### 4.3.1 Wafer Product

- 4.3.1.1 The product should be **vacuum sealed in dry pack** and kept in an environmentally controlled area within  $15^{\circ}\text{C} \sim 35^{\circ}\text{C}$  and  $\leq 60\%\text{RH}$ , and besides, should be used within 6 months.
- 4.3.1.2 The package assembly process must be finished within 7 days.
- 4.3.1.3 To reduce the risk of containment or oxidation, the residual wafer product must be kept in Nitrogen (N₂) purge cabinet within 20°C ~ 30°C or well **vacuum sealed** in dry pack once again.

#### 4.4 Reflow Profile Suggestion

HYCON products are all green products (Halogen Free, Pb-Free), the reflow profile suggestion refers to J-STD-020 as below:



#### Note:

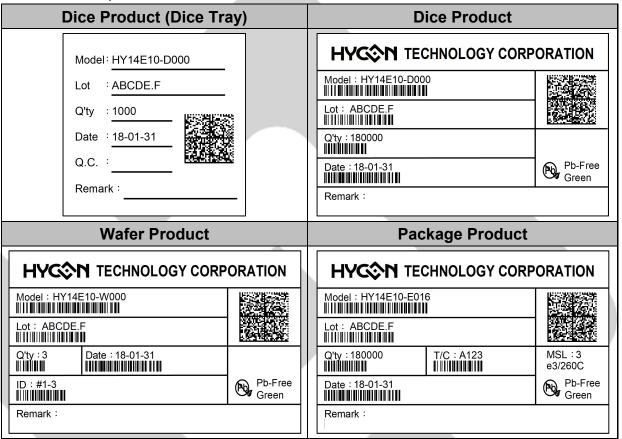
- 1. Tsmin: Preheat/Soak Temperature Min
- 2. Tsmax: Preheat/Soak Temperature Max
- 3. TL: Liquidous Temperature
- 4. Tp: Peak Temperature
- 5. ts: Preheat/Soak Time from Tsmin to Tsmax
- 6. tL: Time maintained above TL
- 7. tp: Time within 5°C of Tp
- 8. Please refer to J-STD-020 for detail



#### 4.5 Product Label System

In order to improve management and traceability, we upgrade label system and introduce 1D and 2D barcode. The barcode label was launched since 2015 Q4. The change of label shall not affect the product function and specification.

#### 4.5.1 Label Example



#### 4.5.2 Symbols of Label

- 4.5.2.1 The "Pb-free, Green" mark means it is Green Product that meets RoHS Directive, SVHC under REACH and Halogen free.
- 4.5.2.2 MSL: Moisture Sensitivity Level.
- 4.5.2.3 Plating Spec:

e3: Pure Sn

e4: Precious Metal.

- 4.5.2.4 260C: Peak temperature of Reflow.
- 4.5.2.5 "MSL", "Plating SPEC" and "260C" are showed on package product label ONLY.
- 4.5.2.6 Above data refers to IPC/JEDEC Joint Standard J-STD-609.



#### 5 Green Product

#### 5.1 Hazardous Substances Control Item within test report

No.	Material & Substance	Legal Reference	Threshold	M.D.L
1	RoHS2.0 Lead (Pb) and its compounds  EU Directive 2011/65/EU California Proposition 65 EU REACH Regulation 86/677/EEC Norway's PoHS		1000ppm (0.1wt%)	≤2ppm
2	RoHS2.0 Mercury (Hg) and its compounds	EU Directive 2011/65/EU EU REACH Regulation TCO 5.2	1000ppm (0.1wt%)	≦2ppm
3	RoHS2.0 Cadmium (Cd) and its compounds	EU Directive 2011/65/EU EU REACH Regulation Norway's PoHS EU Directive 98/101/EC	100ppm (0.01wt%)	≦2ppm
4	RoHS2.0 Hexavalent chromium (Cr <sup>6+</sup> ) compounds	EU Directive 2011/65/EU EU REACH Regulation	1000ppm (0.1wt%)	≦2ppm
5	RoHS2.0 Polybrominated Biphenyls (PBBs)	EU Directive 2011/65/EU EU REACH Regulation	1000ppm (0.1wt%)	≦5ppm
6	RoHS2.0 Polybrominated Diphenyl Ethers (PBDEs) (PBDEs,PBBE,PBDOs,PBBOs, DecaBDE)	EU Directive 2011/65/EU EU REACH Regulation	1000ppm (0.1wt%)	≦5ppm
7	RoHS2.0 Phthalates, e.g.:  Di (2-ethylhexyl) Phthalate (DEHP) Di-n-butyl Phthalate (DBP) Butyl Benzyl Phthalate (BBP) Diisobutyl Phthalate (DIBP) Di-iso-nonyl Phthalate (DINP) Diisodecyl phthalate (DINP) Dii-n-hexyl Phthalate (DINP)	(EU) 2015/863/EU, 2011/65/EU JIG-101 Ed 4.1 Canadian Environmental Protection Act OSPAR	1000ppm (0.1wt%)	≦50ppm
8	Halogen Free Bromine (Br)	<b>IEC 61249-2-21</b> JPCA-ES01 2003	900ppm (0.09 wt%)	≦50ppm
9	Halogen Free Chlorine (CI)	IEC 61249-2-21 JPCA-ES01 2003	900ppm (0.09 wt%)	≦50ppm
10	Halogen Free Total Halogen Contained (CI+Br)	IEC 61249-2-21 JPCA-ES01 2003	1500 ppm (0.15wt%)	≦50ppm
11	Perfluorooctyl acid (PFOA) and individual salts and esters of PFOA Perfluorooctane Sulphnate (PFOS) related substances,	2006/122/EC (EU) 757/2010 (EU) 2020/784 Norway PoHS Stockholm Convention SONY GP (SS-00259)	25 ppb (0.000025wt%)	≦10ppm
12	Halogenated Flame Restardants, e.g.:  ■ Hexabromocyclododecane (HBCCD)  ■ TBBP-A	(EU) 2016/293 Stockholm Convention Norway PoHS JIG-101 Ed 4.1 SONY GP (SS-00259)	Forbidden(N.D)	≦5ppm
13	Ozone Depleting Substances:  Chlorofluorocarbons (CFCs) Hydrochlorofluorocarbons (HCFCs) Halons Bromodifluoromethane and Isomers (HBFCs) Hydrofluorocarbon (HFC) and Perfluorocarbons (PFC) Other ozone depleting substances	Montreal Protocol Annex A, B, C JIG-101 Ed 4.1	Forbidden(N.D)	≦1ppm
14	TSCA  Decabromodiphenyl ether (DecaBDE) Phenol, isopropylated phosphate (3:1) [PIP (3:1)] Pentachlorothiophenol (PCTP) Hexachlorobutadiene (HCBD) 2,4,6-tris(tert-butyl) phenol (2,4,6-TTBP)	Toxic Substances Control Act (TSCA) section 6(h)	Prohibited Prohibited 0.1 wt% Prohibited 0.3 wt%	
15	SVHC (Substance of Very High Concern) under REACH (Registration, Evaluation, Authorization and Restriction of Chemicals) latest version of restricted substances and prescribed regulations Refer to <a href="http://echa.europa.eu/candidate-list-table">http://echa.europa.eu/candidate-list-table</a>	REACH Regulation (EC)	1000 ppm (0.1 wt%)	

Third-Party Test Reports provided by our suppliers and updated within 14 days after the original report test date plus 12-months are available upon customer request

The "not contained" means equal or less than the defined threshold in the material. The defined threshold is 0.1 % (1,000 ppm) per weight, unless otherwise specified. Our products are in compliance with the SVHC under REACH current version of restricted substances and prescribed regulations.

HYCON Environmental Policy : <a href="http://www.hycontek.com/en/company-en/1781#tab2">http://www.hycontek.com/en/company-en/1781#tab2</a>

The SVHC is *not contained* in HYCON Technology Corporation's product based on our supply chain's information.



#### 5.2 Restricted Use of Conflict Minerals

HYCON Technology Corporation hereby declares all products supplied to customers are of conflict-free minerals.

Over the past few years, provoking society and environmental problems generated from manufacturing product raw materials and processes has grabbed the public's attention. Minerals from Democratic Republic of the Congo (DRC) even raised serious armed conflicts. Despite HYCON Technology Corporation does not procure minerals directly ourselves, still asserting the concept of sustainable corporate development and social responsibility and respects international human rights. HYCON Technology Corporation is in support of not using conflict minerals and is committed to fully survey supply chain, taking social and environmental responsibilities together with joint vendors, thus hereby declares:

- 1. Not to purchase conflict minerals from mines in the conflict regions.
- 2. Demand joint vendors not to use conflict minerals and to disclose the origin of Tantalum (Ta), Tin (Sn), Gold (Au), Tungsten (W), Cobalt (Co), Palladium (Pd) used in products and to provide restricted use of conflict minerals letter of commitment.
- Demand joint vendors to formally convey the request of Restricted Use of Conflict Minerals to their upstream suppliers.
- 4. Conflict-Free Minerals Policy: <a href="http://www.hycontek.com/en/company-en/1781#tab4">http://www.hycontek.com/en/company-en/1781#tab4</a>